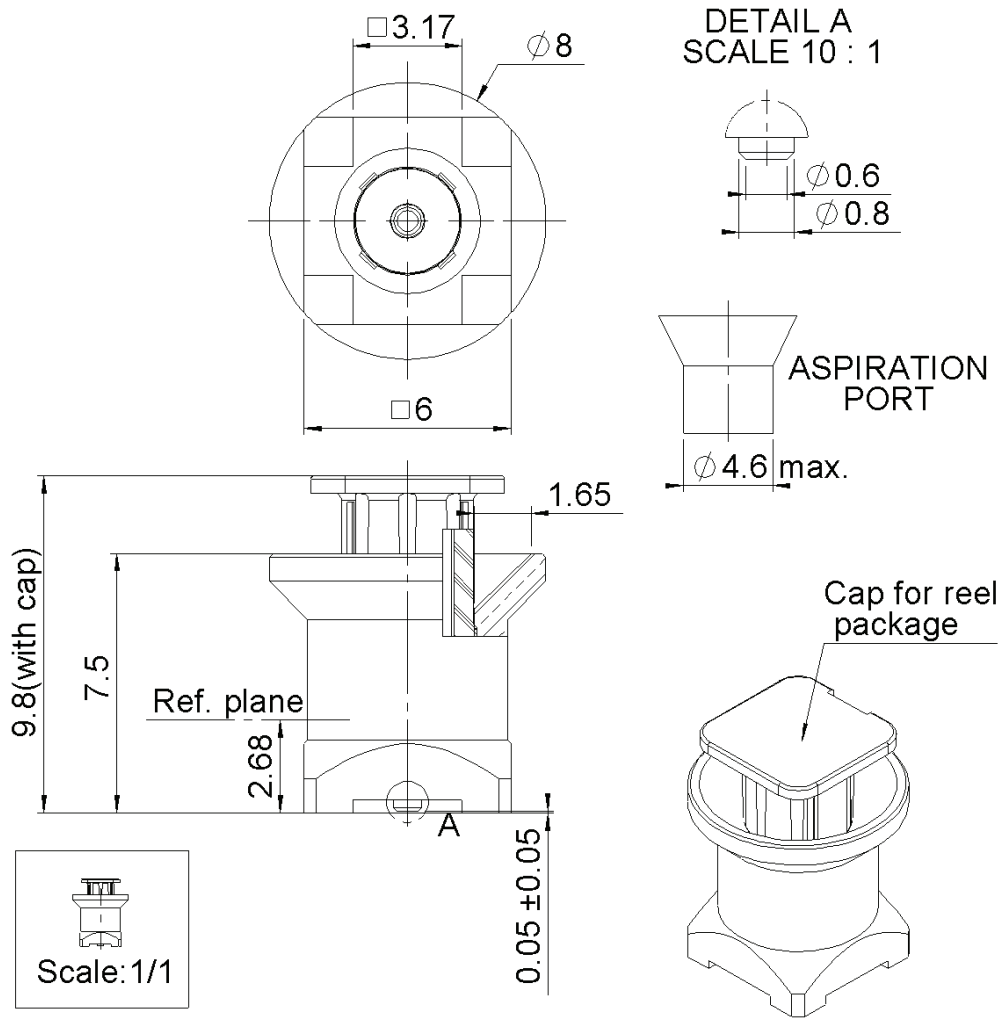


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All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
Body	<b>BRASS</b>	<b>NPGR</b>
Center contact	<b>BRASS</b>	<b>NPGR</b>
Outer contact		
Insulator	<b>PTFE/LCP/PEEK</b>	
Gasket		
Others parts	<b>PTFE/LCP/PEEK</b>	
-	-	-
-	-	-

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**PACKAGING**

Standard	Unit	Other
400	Contact us	Contact us

**ELECTRICAL CHARACTERISTICS**

Impedance		<b>50</b>	Ω
Frequency		<b>0-6</b>	GHz
VSWR	<b>1.25*</b> +	<b>0.0000</b>	x F(GHz) Maxi
Insertion loss		<b>0.15*</b>	√F(GHz) dB Maxi
RF leakage	- (	<b>NA</b>	- F(GHz)) dB Maxi
Voltage rating		<b>335</b>	Veff Maxi
Dielectric withstanding voltage		<b>1000</b>	Veff mini
Insulation resistance		<b>5000</b>	MΩ mini

**MECHANICAL CHARACTERISTICS**

Center contact retention			
Axial force – Mating End		<b>7</b>	N mini
Axial force – Opposite end		<b>7</b>	N mini
Torque		<b>NA</b>	N.cm mini
Recommended torque			
Mating		<b>NA</b>	N.cm
Panel nut		<b>NA</b>	N.cm
Mating life		<b>100</b>	Cycles mini
Weight		<b>1.3550</b>	g

**ENVIRONMENTAL**

Operating temperature	<b>-55/+165</b>	°C
Hermetic seal	<b>NA</b>	Atm.cm3/s
Panel leakage	<b>NA</b>	

**SPECIFICATION**

**OTHER CHARACTERISTICS**

Assembly instruction:

Others:

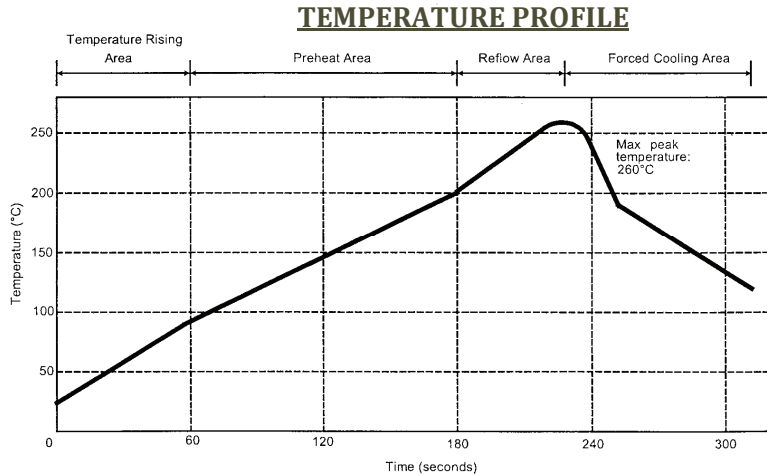
- \*VSWR: up to 3 GHz; 3-6GHz, 1.35max**
- \*Coaxial Transmission Line Only**
- \*Slide type receptacle+Bullet+Snap type**
- Typical VSWR(Board to Board connection):**
- 0-3GHz, 1.2max**
- Power handling (typical) :**
- >300W@2.7GHz at 25°C; >200W@2.7GHz at 85°C**
- Radial working angle: 3° min**
- Axial working range: 2mm**

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## SOLDER PROCEDURE

1. Deposit solder paste ‘SnAg4Cu0.5’ on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm ( 5.850 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
4. The cleaning of printed circuit boards is not obliged .

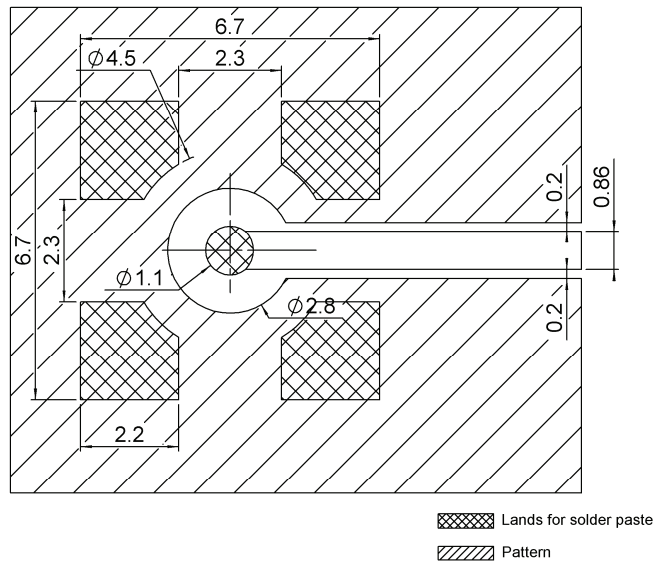
Verification of solder joints and position of the component by visual inspection.



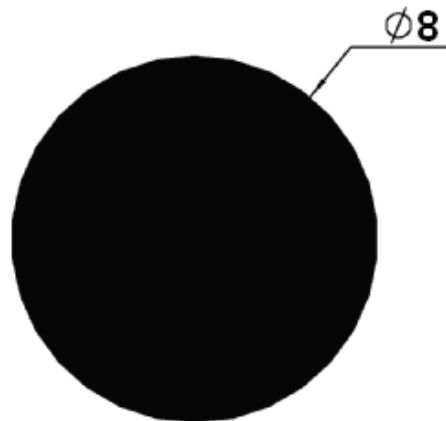
Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260 °C	10	sec
Min dwell time @235 °C	20	sec
Max dwell time @235 °C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100 °C	420	sec

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PCB

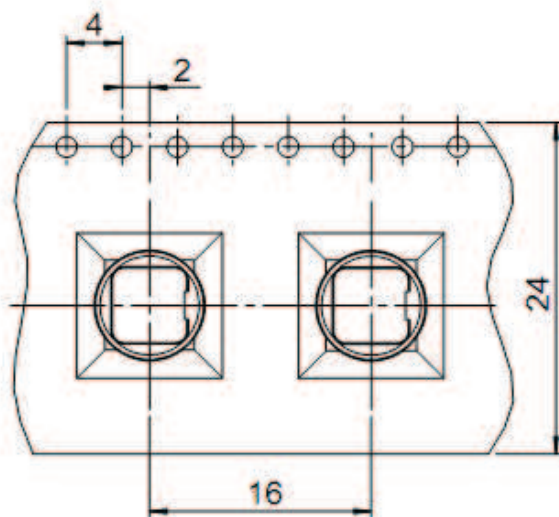
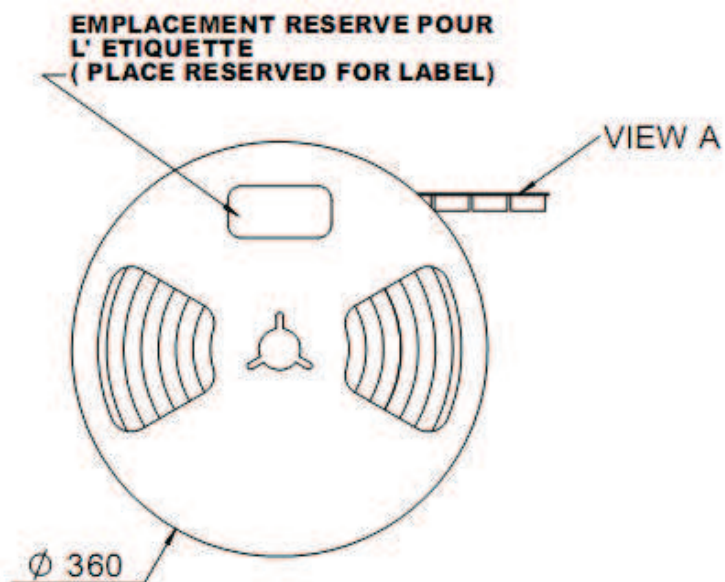


Shadow of receptacle for video camera



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PACKAGE



VIEW A